



# **NPN General Purpose Amplifier**

This device is for use as a medium power amplifier and switch requiring collector currents up to 500 mA. Sourced from Process 19. See PN2222A for characteristics.

#### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{CEO}$	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	75	V
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V
I <sub>C</sub>	Collector Current - Continuous	1.0	Α
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

# Thermal Characteristics TA = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
		TN2219A	
P <sub>D</sub>	Total Device Dissipation	1.0	W
	Derate above 25°C	8.0	W/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	°C/W

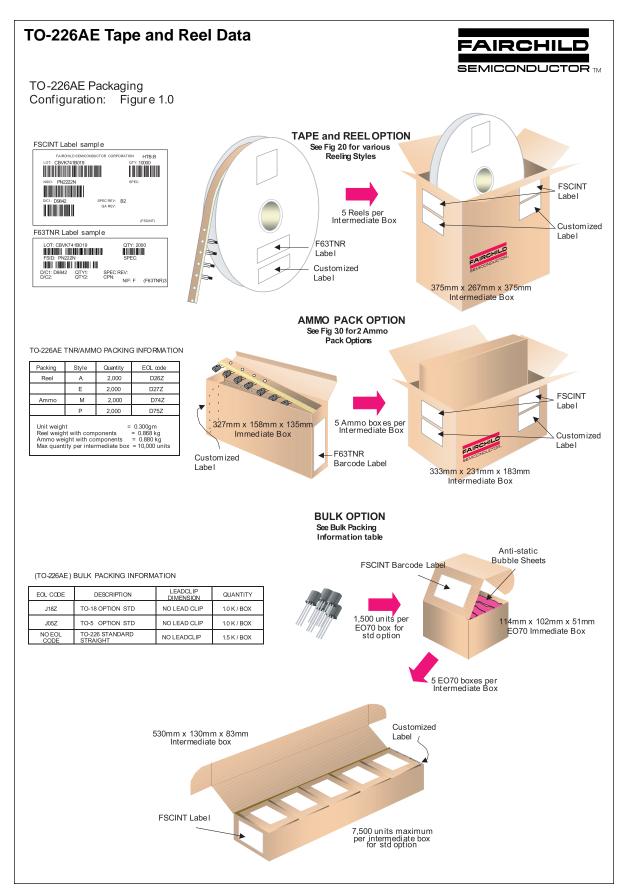
<sup>1)</sup> These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# NPN General Purpose Amplifier (continued)

Parameter	Test Conditions	Min	Max	Units
RACTERISTICS				
Collector-Emitter Breakdown Voltage*	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0	40		V
, and the second		75		V
•	•			V
•	, -	0.0	10	nA
			_	nA
Collector Cuton Current			_	μA
Emitter Cutoff Current	$V_{EB} = 3.0 \text{ V}, I_{C} = 0$		10	nΑ
Base Cutoff Current			20	nA
ACTERISTICS	1 - 0.1 mA \/ - 10 \/	25		
DC Current Gain				
	$I_{\rm C} = 10  \text{mA},  V_{\rm CE} = 10  \text{V}$	75		
	$I_C = 150 \text{ mA}, V_{CE} = 10 \text{ V}$	100	300	
	$I_C = 150 \text{ mA}, V_{CE} = 1.0 \text{ V}$	50		
		40	0.0	
Collector-Emitter Saturation Voltage*				V
Base-Emitter Saturation Voltage*		0.6	1.2	V
	$I_C = 500 \text{ mA}, I_B = 5.0 \text{ mA}$		2.0	V
GNAL CHARACTERISTICS	V 40 V 1 0 ( 400 III-		0.0	
· · ·				pF
Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0, f = 100 \text{ kHz}$		25	
-				pF
Small-Signal Current Gain	$I_C = 1.0 \text{ mA}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ kHz}$	50	300	pr
	$I_C = 10 \text{ mA}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ kHz}$	50 75	375	
Small-Signal Current Gain  Collector Base Time Constant  Noise Figure	, ,			pS dB
	Base Cutoff Current  ACTERISTICS  DC Current Gain  Collector-Emitter Saturation Voltage*  Base-Emitter Saturation Voltage*			

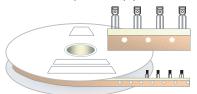
<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%



## **TO-226AE Tape and Reel Data, continued**

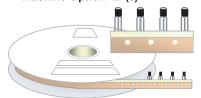
**TO-226AE Reeling Style Configuration:** Figure 2.0

### Machine Option "A" (H)



Style "A" D26Z, D70Z (s/h)

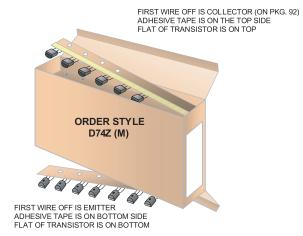
### Machine Option "E"(J)



Style "E" D27Z, D71Z (s/h)

# TO-226AE Radial Ammo Packaging

Configuration: Figure 3.0



FIRST WIRE OFF IS EMITTER (ON PKG. 92) ADHESIVE TAPE IS ON THE TOP SIDE FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

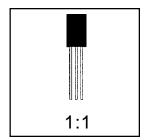
#### **TO-226AE Tape and Reel Data, continued** TO-226AE Tape and Reel Taping Dimension Configuration: Figure 4.0 ITEM DESCRIPTION SYMBOL DIMENSION Base of Package to Lead Bend 0.098 (max) Component Height Hb 1.078 (+/- 0.050) User Direction of Feed 0.630 (+/- 0.020) Lead Clinch Height HO Component Base Height H1 0.748 (+/- 0.020) Component Alignment (side/side) Pd 0.040 (max) 0.031 (max) Component Alignment ( front/back ) Hd 0.500 (+/- 0.020) Component Pitch РО Feed Hole Pitch 0.500 (+/- 0.008) Hole Center to First Lead P1 0.150 (+0.009, -0.010) Hole Center to Component Center P2 0.247 (+/- 0.007) Lead Spread F1/F2 0.104 (+/- 0 010) Lead Thickness d 0.018 (+0.002, -0.003) 0.429 (max) Cut Lead Length Taped Lead Length 0.209 (+0.051, -0.052) L1 Taped Lead Thickness 0.032 (+/- 0.006) Carrier Tape Thickness t1 0.021 (+/- 0.006) TO-226AE Reel Carrier Tape Width 0.708 (+0.020, -0.019) W Configuration: Figure 5.0 Hold - down Tape Width wo 0.236 (+/- 0.012) 0.035 (max) Hold - down Tape position W1 0.360 (+/- 0.025) W2 Feed Hole Position 0.157 (+0.008, -0.007) Sprocket Hole Diameter DO 0.004 (max) Lead Spring Out S Note: All dmensions are in inches. D4 ITEM DESCRIPTION SYMBOL MINIMUM MAXIMUM Red Diameter 13975 14025 Arbor Hole Diameter (Standard) 1.200 D2 1.160 D2 0.650 0.700 (Small Hole) Core Diameter D3 3.100 3.300 Hub Recess Inner Diameter D4 3.100 Hub Recess Depth W 1 0.370 0.570 Range to Range Inner Width W2 1.630 1.690 Hub to Hub Center Width 2.090 WЗ Note: All dimensions are inches

# **TO-226AE Package Dimensions**



# TO-226AE (FS PKG Code 95, 99)

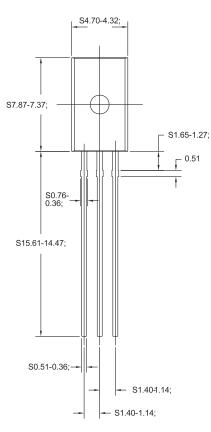


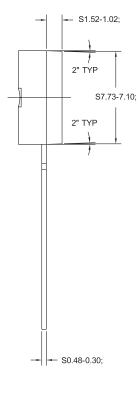


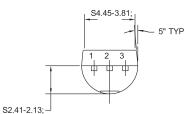
Scale 1:1 on letter size paper

Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.300









For leadformed option ordering, refer to Tape & Reel data information.

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